Electronic Component Package Standard

Specification for Surface Mount Integrated Circuit Packages

Publication ECP-2024-SMD-IC
Revision 3.1
Effective Date: 1 January 2024

This standard specifies the dimensions, tolerances, and marking requirements for surface mount integrated circuit packages. It covers small outline, quad flat, and ball grid array packages with lead counts from 8 to 256. Compliance with this standard ensures interchangeability between packages from different manufacturers.

Table of Contents

1 Scope 1
2 Normative References 1
3 Terms and Definitions 2
4 Package Outlines 3
5 Lead Configuration 5
6 Marking 6
7 Moisture Sensitivity 7
8 Thermal Characteristics 8
9 Mechanical Tests 9
10 Quality Assurance 10
Annex A Land Pattern Recommendations 11
Annex B Tape and Reel Packaging 12

1 Scope

This standard applies to surface mount integrated circuit packages intended for reflow soldering. It does not apply to through hole packages, chip scale packages, or bare die. The standard defines mechanical outlines, lead finish, marking, and moisture sensitivity classification.

2 Normative References

The following documents are referenced in this standard. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document applies.

JEDEC MS-012 Small Outline Integrated Circuits
JEDEC MO-220 Quad Flat No Lead Package
JEDEC MO-299 Fine Pitch Ball Grid Array
IPC-7351 Generic Requirements for Surface Mount Design and Land Pattern Standard
IPC/JEDEC J-STD-020 Moisture Reflow Sensitivity Classification
IEC 60068-2-58 Environmental Testing Part 2 Test Soldering Resistance of Surface Mounting Devices

3 Terms and Definitions

For the purposes of this standard, the following terms and definitions apply.

Body size The overall dimensions of the package body, excluding leads, solder balls, and any protrusions.

Lead pitch The distance between the centerlines of adjacent leads, measured at the base material.

Coplanarity The maximum vertical deviation of any lead or solder ball from the seating plane.

Seating plane The plane on which the package rests when mounted, defined by the bottom surface of the package body.

Standoff The distance between the seating plane and the bottom of the package body.

Moisture sensitivity level The classification of a package according to its susceptibility to moisture absorption during reflow soldering.

4 Package Outlines

4.1 Small Outline Packages

Small outline packages have gull wing leads on two sides. The body size and lead pitch determine the package designation.

Designation	Body Width (mm)	Lead Pitch (mm)	Lead Count
SOP-8	3.90	1.27	8
SOP-14	3.90	1.27	14
SOP-16	3.90	1.27	16
SOP-20	7.50	1.27	20
SOP-24	7.50	1.27	24
SOP-28	7.50	1.27	28
TSSOP-8	3.00	0.65	8
TSSOP-14	3.00	0.65	14
TSSOP-16	3.00	0.65	16
TSSOP-20	4.40	0.65	20
TSSOP-24	4.40	0.65	24
TSSOP-28	4.40	0.65	28

4.2 Quad Flat Packages

Quad flat packages have leads on all four sides. The lead count is always a multiple of four.

Designation	Body Size (mm)	Lead Pitch (mm)	Lead Count
QFP-32	7.00 x 7.00	0.80	32
QFP-44	10.00 x 10.00	0.80	44
QFP-48	7.00 x 7.00	0.50	48
QFP-64	10.00 x 10.00	0.50	64
QFP-80	12.00 x 12.00	0.50	80
QFP-100	14.00 x 14.00	0.50	100
QFP-128	14.00 x 14.00	0.40	128
QFP-144	20.00 x 20.00	0.50	144
QFP-176	24.00 x 24.00	0.50	176
QFP-208	28.00 x 28.00	0.50	208

4.3 Ball Grid Array Packages

Ball grid array packages have solder balls on the bottom surface in a regular grid pattern.

Designation	Body Size (mm)	Ball Pitch (mm)	Ball Count
BGA-64	9.00 x 9.00	1.00	64
BGA-100	11.00 x 11.00	1.00	100
BGA-144	13.00 x 13.00	1.00	144
BGA-196	15.00 x 15.00	1.00	196
BGA-256	17.00 x 17.00	1.00	256
BGA-324	19.00 x 19.00	1.00	324
BGA-400	21.00 x 21.00	1.00	400
BGA-484	23.00 x 23.00	1.00	484
BGA-576	25.00 x 25.00	1.00	576
BGA-676	27.00 x 27.00	1.00	676

5 Lead Configuration

Lead numbering shall start at pin 1 and proceed counterclockwise when viewed from the top of the package. Pin 1 is identified by a dot, chamfer, or notch on the package body.

6 Marking

Each package shall be marked with the following information:

- Manufacturer identification
- Part number
- Date code in the format YYWW
- Pin 1 indicator

Marking shall be legible after reflow soldering and cleaning. Laser marking is preferred for packages with a body size smaller than 5 mm.

7 Moisture Sensitivity

Packages are classified according to IPC/JEDEC J-STD-020. The moisture sensitivity level determines the floor life and the required baking conditions before reflow.

Level	Floor Life	Baking Required
1	Unlimited at 30 C / 85 % RH	No
2	1 year at 30 C / 60 % RH	No
2a	4 weeks at 30 C / 60 % RH	No
3	168 hours at 30 C / 60 % RH	No
4	72 hours at 30 C / 60 % RH	No
5	48 hours at 30 C / 60 % RH	No
5a	24 hours at 30 C / 60 % RH	No
6	Time on label	Yes

8 Thermal Characteristics

Thermal resistance values are given for a standard test board with a single signal layer and no thermal vias. Actual values depend on the board design and the presence of thermal vias.

Designation	Junction to Ambient (C/W)	Junction to Case (C/W)
SOP-8	160	45
SOP-14	120	40
SOP-16	110	38
SOP-20	95	35
SOP-24	85	32
SOP-28	80	30
TSSOP-8	180	50
TSSOP-14	140	45
TSSOP-16	130	42
TSSOP-20	115	40
TSSOP-24	105	38
TSSOP-28	100	36
QFP-32	90	25
QFP-44	80	22
QFP-48	75	20
QFP-64	65	18
QFP-80	58	16
QFP-100	50	14
QFP-128	45	12
QFP-144	40	11
QFP-176	36	10
QFP-208	32	9
BGA-64	55	15
BGA-100	48	13
BGA-144	42	12
BGA-196	38	11
BGA-256	34	10
BGA-324	30	9
BGA-400	28	8
BGA-484	26	7
BGA-576	24	7
BGA-676	22	6

9 Mechanical Tests

Packages shall pass the following mechanical tests:

- Vibration, 10 to 2000 Hz, 20 g
- Mechanical shock, 1500 g, 0.5 ms
- Bend test, 2 mm deflection
- Solderability, 95 % coverage minimum

10 Quality Assurance

Each lot shall be accompanied by a certificate of conformance. Sampling shall follow ANSI/ASQ Z1.4 with an acceptance quality limit of 0.65 %.

Annex A Land Pattern Recommendations

Land patterns are recommended for reflow soldering. The values are given for nominal package dimensions.

Designation	Pad Length (mm)	Pad Width (mm)	Pad Spacing (mm)
SOP-8	1.55	0.60	5.40
SOP-14	1.55	0.60	5.40
SOP-16	1.55	0.60	5.40
SOP-20	1.55	0.60	9.00
SOP-24	1.55	0.60	9.00
SOP-28	1.55	0.60	9.00
TSSOP-8	1.45	0.40	4.40
TSSOP-14	1.45	0.40	4.40
TSSOP-16	1.45	0.40	4.40
TSSOP-20	1.45	0.40	5.80
TSSOP-24	1.45	0.40	5.80
TSSOP-28	1.45	0.40	5.80
QFP-32	1.60	0.45	8.40
QFP-44	1.60	0.45	11.40
QFP-48	1.60	0.30	8.40
QFP-64	1.60	0.30	11.40
QFP-80	1.60	0.30	13.40
QFP-100	1.60	0.30	15.40
QFP-128	1.60	0.25	15.40
QFP-144	1.60	0.30	21.40
QFP-176	1.60	0.30	25.40
QFP-208	1.60	0.30	29.40
BGA-64	0.60	0.60	1.00
BGA-100	0.60	0.60	1.00
BGA-144	0.60	0.60	1.00
BGA-196	0.60	0.60	1.00
BGA-256	0.60	0.60	1.00
BGA-324	0.60	0.60	1.00
BGA-400	0.60	0.60	1.00
BGA-484	0.60	0.60	1.00
BGA-576	0.60	0.60	1.00
BGA-676	0.60	0.60	1.00

Annex B Tape and Reel Packaging

Packages are supplied on embossed carrier tape wound on reels. The tape width and pocket pitch depend on the package size.

Designation	Tape Width (mm)	Pocket Pitch (mm)	Reel Diameter (mm)	Quantity per Reel
SOP-8	12	8	330	2500
SOP-14	16	8	330	2500
SOP-16	16	8	330	2500
SOP-20	24	12	330	1000
SOP-24	24	12	330	1000
SOP-28	24	12	330	1000
TSSOP-8	12	8	330	3000
TSSOP-14	16	8	330	3000
TSSOP-16	16	8	330	3000
TSSOP-20	16	8	330	3000
TSSOP-24	16	8	330	3000
TSSOP-28	16	8	330	3000
QFP-32	24	12	330	1000
QFP-44	24	12	330	1000
QFP-48	24	12	330	1000
QFP-64	24	12	330	1000
QFP-80	32	16	330	500
QFP-100	32	16	330	500
QFP-128	32	16	330	500
QFP-144	32	16	330	500
QFP-176	44	24	330	500
QFP-208	44	24	330	500
BGA-64	16	12	330	1000
BGA-100	16	12	330	1000
BGA-144	16	12	330	1000
BGA-196	24	12	330	1000
BGA-256	24	12	330	1000
BGA-324	24	12	330	1000
BGA-400	32	16	330	500
BGA-484	32	16	330	500
BGA-576	32	16	330	500
BGA-676	32	16	330	500